

### Description

The SX3407AI uses advanced Trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -30V$   $I_D = -4.8A$

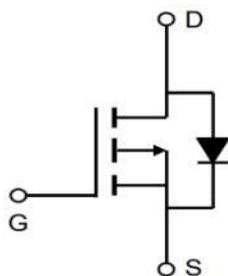
$R_{DS(ON)} < 55m\Omega @ V_{GS} = 10V$

### Application

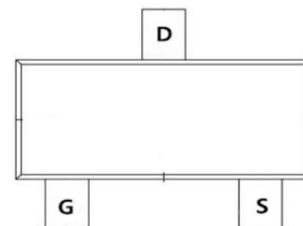
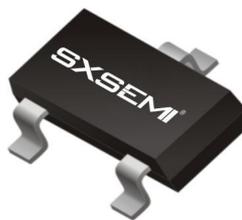
Battery protection

Load switch

Uninterruptible power supply



SOT-23



### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Max.	Units
VDSS	Drain-Source Voltage	-30	V
VGSS	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4.8	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.3	A
IDM	Pulsed Drain Current <sup>note1</sup>	-20.4	A
P <sub>D</sub>	Power Dissipation $T_A = 25^\circ C$	2.15	W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	104	$^\circ C/W$
R <sub>θJC</sub>	Thermal Resistance from Junction to Ambient <sup>2</sup>	125	$^\circ C/W$
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30	-	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1	μA
IGSS	Gate-Source Leakage	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
VGS(th)	Gate-Source Threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1	-1.5	-2.5	V
RDS(on)	Drain-Source on-State Resistance <sup>3</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.1A	-	40	55	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A	-	54	65	
Ciss	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -15V, f = 1.0MHz	-	530	-	pF
Coss	Output Capacitance		-	70	-	
Crss	Reverse Transfer Capacitance		-	56	-	
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V, I <sub>D</sub> = -4.1A	-	6.8	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	1.0	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	1.4	-	
td(on)	Turn-on Delay Time	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V , R <sub>L</sub> = 15Ω,R <sub>GEN</sub> = 2.5Ω	-	14	-	ns
t <sub>r</sub>	Rise Time		-	61	-	
td(off)	Turn-off Delay time		-	19	-	
t <sub>f</sub>	Fall Time		-	10	-	
VSD	Diode Forward Voltage <sup>3</sup>	I <sub>S</sub> = -4.1A, V <sub>GS</sub> = 0V	-	-	-1.2	V
IS	Continuous Source Current		-	-	-4.1	A

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

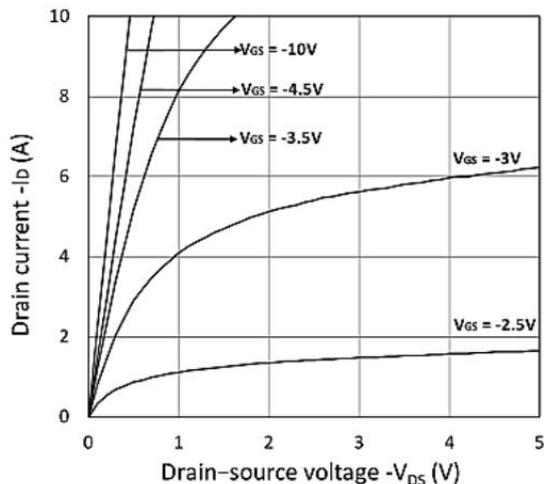


Figure 1. Output Characteristics

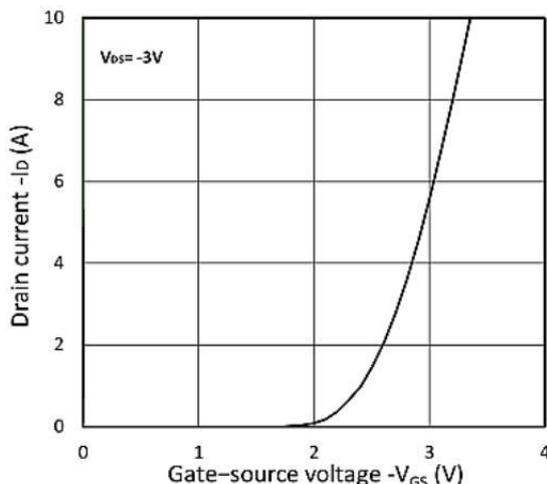


Figure 2. Transfer Characteristics

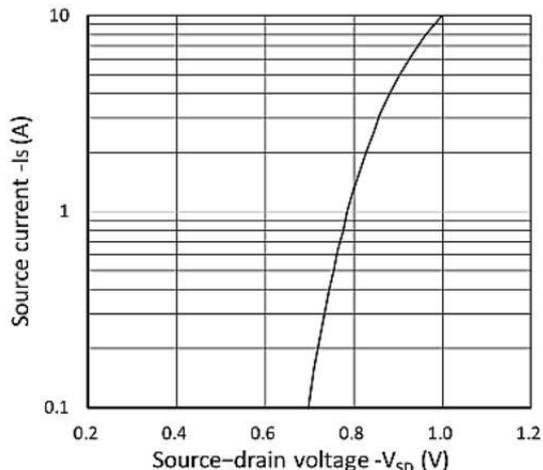


Figure 3. Forward Characteristics of Reverse

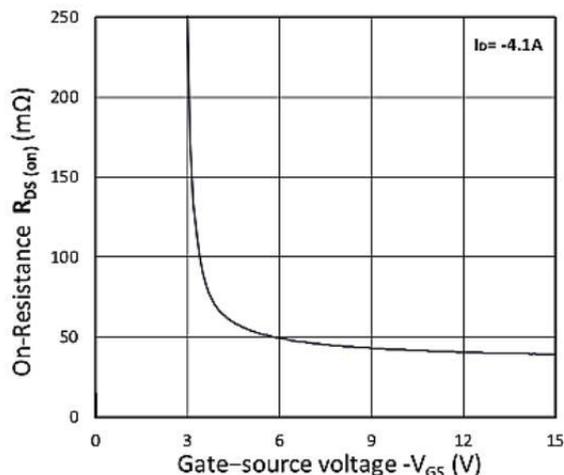


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

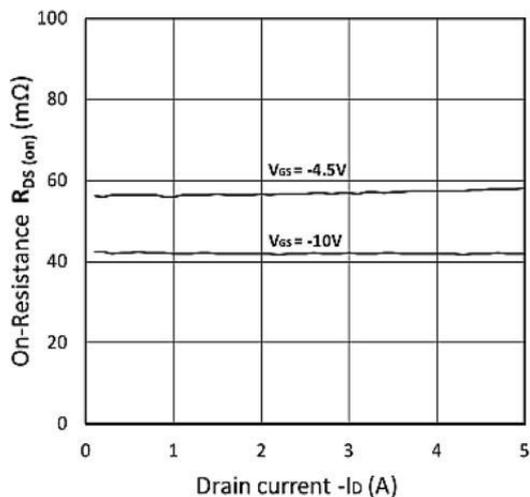


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

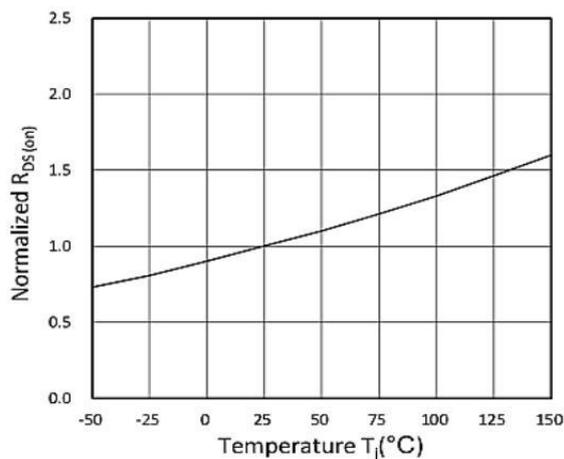


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

Typical Characteristics

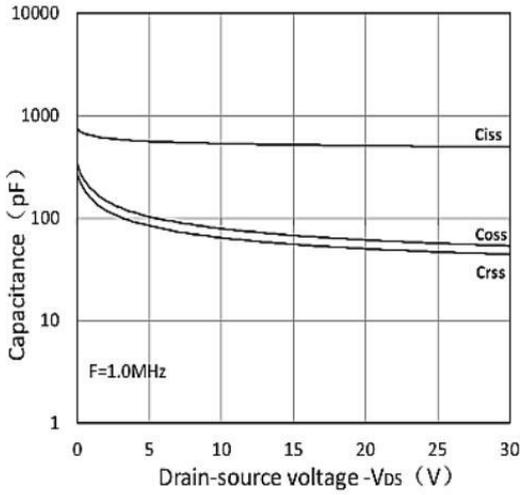


Figure 7. Capacitance Characteristics

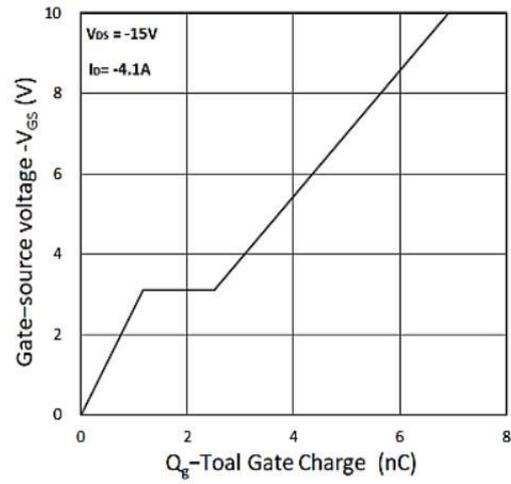


Figure 8. Gate Charge Characteristics

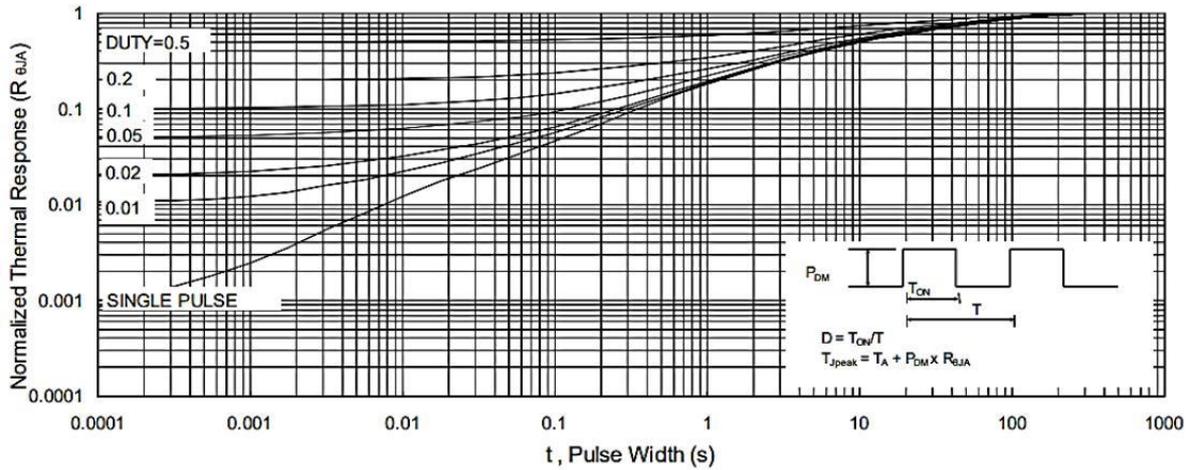


Figure 9 Normalized Maximum Transient Thermal Impedance

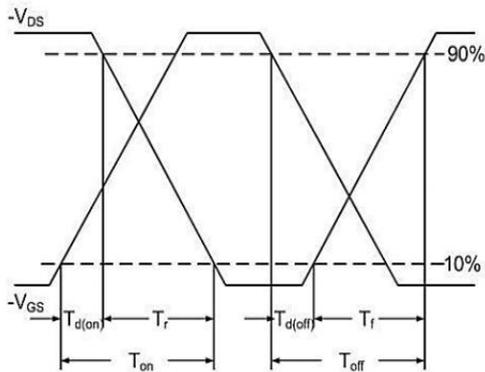


Figure.10 Switching Time Waveform

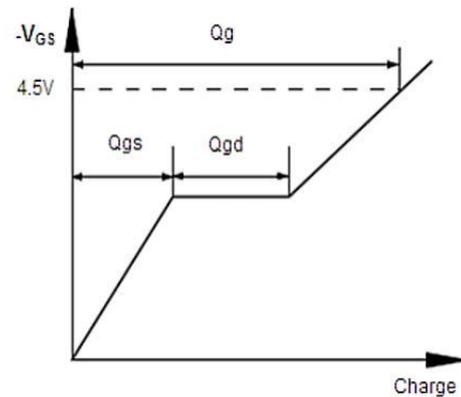
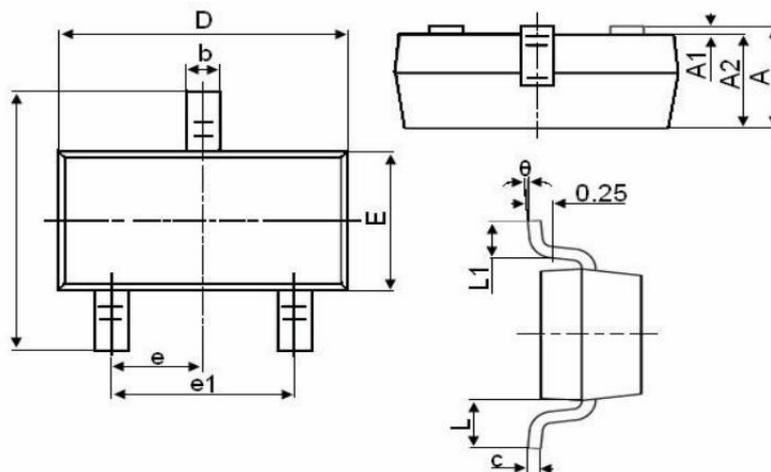


Figure.11 Gate Charge Waveform

**Package Mechanical Data-SOT23-XC-Single**



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
theta	0°	8°

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT23		3000